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LEE(10) **Pub. No.: US 2023/0230980 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **ARRAY SUBSTRATE STRUCTURE**(30) **Foreign Application Priority Data**(71) Applicant: **InnoLux Corporation**, Miao-Li County
(TW)

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(72) Inventor: **Kuan-Feng LEE**, Miao-Li County
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(2013.01)(21) Appl. No.: **18/188,009**(22) Filed: **Mar. 22, 2023****Related U.S. Application Data**(63) Continuation of application No. 17/249,801, filed on
Mar. 15, 2021, now Pat. No. 11,631,728, which is a
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Nov. 11, 2019, now Pat. No. 10,978,533, which is a
continuation of application No. 15/629,912, filed on
Jun. 22, 2017, now Pat. No. 10,504,982.(57) **ABSTRACT**

An array substrate structure is provided, which includes a substrate with a first surface and a second surface opposite to the first surface. A first TFT is on the first surface of the substrate, and a second TFT is on the second surface of the substrate. A through via passes through the substrate, and the first TFT is electrically connected to the second TFT through the through via.

